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Bias Dependence of the Electrical Spin Injection into GaAs from Co-Fe-B/MgO Injectors with Different MgO Growth Processes

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We investigate the influence of the MgO growth process on the bias dependence of the electrical spin injection from a Co-Fe-B/MgO spin injector into a GaAs-based light-emitting diode (spin LED). With this aim, textured MgO tunnel barriers are fabricated either by sputtering or molecular-beam-epitaxy (MBE) methods. For the given growth parameters used for the two techniques, we observe that the circular polarization of the electroluminescence emitted by spin LEDs is rather stable as a function of the injected current or applied bias for the samples with sputtered tunnel barriers, whereas the corresponding circular polarization decreases abruptly for tunnel barriers grown by MBE. We attribute these different behaviors to the different kinetic energies of the injected carriers linked to differing amplitudes of the parasitic hole current flowing from GaAs to Co-Fe-B in both cases.

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I. INTRODUCTION

The use of the electron spin instead of its charge to design electronic devices with alternative functionalities [1] has stimulated intense investigation of spin properties in hybrid ferromagnetic–semiconductor systems in the past decade [2–10]. In spin light-emitting diodes (spin LEDs) based on a quantum well (QW), the circular polarization of the emitted electroluminescence reflects the electron spin polarization injected in the conduction band of the device due to optical selection rules [11]. This link allows us to quantify the efficiency of the spin injection. For future applications, these spin LEDs present the ability to transfer the electron spin information into the photon helicity and could be used in potential optical telecommunication devices [12–14].

Among all of the methods proposed to date to generate spin-polarized currents in semiconductors, an efficient solution at room temperature consists of injecting spin-polarized electrons from a ferromagnetic injector through a tunnel barrier (e.g., an oxide tunnel barrier like MgO [6,15–21]), in order to overcome the problem of conductivity mismatch between the metal and the semiconductor [22]. Thus far, in-plane CoFe/MgO [6] and in- and out-of-plane Co-Fe-B/MgO [16–21] injectors have exhibited the highest spin-injection yield into (Al,Ga)As, at both low temperature and room temperature under a perpendicular magnetic field at saturation. The electroluminescence polarization can reach values of up to 50% at 100 K and 32% at 300 K for CoFe/MgO in-plane injectors [6] and 37%–42% at 25 K at saturation for Co-Fe-B/MgO in-plane spin injectors [16,17]. This large polarization could result from spin-filtering effects linked to the nonequivalent attenuation of the evanescent wave functions inside the MgO barrier depending on their symmetries [23].

For practical applications, the influence of the bias and the current on the electrical spin-injection efficiency in such devices has to be understood. To date, it has been investigated in different types of hybrid ferromagnetic–semiconductor systems: unipolar devices studied with the Kerr rotation technique [24], nonlocal four-terminal full-electrical devices and three-terminal full-electrical [25,26] or bipolar devices such as spin LEDs [6,7,27–31]. Among these studies, several investigations have been performed on spin LEDs based on Schottky [7,28,29,31], Al2O3 [27,30], or MgO barriers [6]. For the final option, a detailed understanding of the dependence of the

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spin-injection efficiency as a function of the bias is still lacking. This dependence may depend on the metal-oxide-semiconductor interface, which has been explored in different systems in view of spin injection and detection[32–36]. In this paper, we investigate the influence of the MgO tunnel-barrier growth process on the current and bias dependence of the electrical spin injection into an (In,Ga)As/GaAs quantum-well light-emitting diode. The properties of the Co-Fe-B/MgO/GaAs interfaces are engineered thanks to the use of two types of growth for the textured MgO tunnel barriers, which are fabricated either by sputtering or by molecular beam epitaxy (MBE).

II. SAMPLES AND EXPERIMENTAL METHODS

The schematics of the spin-LED structure is displayed in Fig. 1(a). The p-i-n LED device grown by MBE contains a single 10-nm In0.1Ga0.9As/GaAs quantum well in the intrinsic region. The full sequence of the semiconductor structure is as follows: p-GaAs:Zn(001) substrate (p = 2 × 10¹⁹ cm⁻³)/500-nm p-GaAs:Be (p = 2 × 10¹⁹ cm⁻³)/200-nm p-GaAs:Be (p = 2 × 10¹⁸ cm⁻³)/50-nm undoped GaAs/10-nm undoped In0.1Ga0.9As/50-nm undoped GaAs/50-nm n-GaAs:Si (n = 10¹⁰ cm⁻³). The LEDs are passivated with arsenic in the semiconductor MBE chamber and then transferred through air into a second MBE-sputtering interconnected system.

The As capping layer is first desorbed at 300°C in the MBE chamber. Two methods are then used to grow the MgO layer. Either the MgO layer is grown by MBE at 250°C after As desorption or we transfer the sample through ultrahigh vacuum to a sputtering chamber to grow the MgO layer (in the latter case, a target of MgO is directly used for sputtering in Ar gas with a pressure of 10⁻² mbar).

In both cases [see Fig. 1(b)], the MgO layer has the same thickness of 2.5 nm, measured by transmission electron microscopy (TEM). Finally, the 3-nm Co0.4Fe0.6B0.2 spin injector and 5-nm Ta protection layer are deposited by sputtering in both cases. Hereafter, we use the terms MBE and sputtering sample to refer to different spin LEDs with different MgO growth processes. 300-μm-diameter circular mesa are then processed using standard UV lithography and etching techniques. Finally, the processed wafers are cut into small pieces to perform rapid temperature annealing at different temperatures for 3 min.

For the polarization-resolved electroluminescence (EL) measurements, the spin LED is placed into a Helmholtz-split magnetic coil providing a maximum magnetic field (B) of 0.8 T normal to the sample plane. The sample is excited with square pulses at 50 kHz (a pulse width of 1 μs) in order to avoid the Joule effect. The EL signal is detected in the Faraday geometry. The EL circular-polarization degree Pc is analyzed through a λ/4 wave plate and a linear analyzer. Pc is defined as Pc = (I⁺ - I⁻)/(I⁺ + I⁻), where I⁺ and I⁻ are the intensities of the right and left circularly polarized components of the luminescence, respectively. The electroluminescence circular polarization Pc associated with the E₁-HH₁ exciton QW (XH) transition corresponds to the electron spin-polarization degree.

III. RESULTS AND DISCUSSION

A. Electroluminescence circular polarization

Figure 1(c) shows a typical cw EL spectra for a sputtering spin LED (annealed at 300°C) acquired under a bias of V = 2.4 V for B = 0.8 T at 25 K. We check to see that the magnetic circular dichroism is less than 1% at 0.8 T [20,37]. The EL polarization reaches Pc = 21.0 ± 1.5% for B = 0.8 T at 25 K, and it is still about Pc = 20.0 ± 1.5% at 250 K (not shown). As expected from optical selection rules [11], the measured EL circular polarization detected along the growth axis increases with the applied longitudinal magnetic field [Fig. 1(d)] due to the progressive increase of the projection of the magnetization along the growth axis.

Note that the maximal applied magnetic field of 0.8 T is not enough to saturate the magnetization along the growth axis. In order to extrapolate Pc at saturation, we multiply Pc (0.8 T) by a factor Msaturation/M(0.8 T) ≈ 1.75 based on the results obtained with a superconducting quantum-interference device on this sample in Ref. [17]. This extrapolation leads to a rough estimation of Pc at a saturation of about 37.0 ± 1.5% at 25 K and 35.0 ± 1.5% at 250 K. Taking into account the spin relaxation during the electron lifetime in the quantum well, by measuring the electron spin lifetime τs and the electron...
lifetime $\tau$ at 25 K [17], one can estimate an injected spin polarization $P_e \sim 51\%$ at 25 K [$P_e = P_c/F$, with $F = 1/(1 + \tau/\tau_s) \sim 0.72$]. This value proves the efficiency and robustness of the spin-injection process into an (In,Ga)As/GaAs QW [4,31,38] with Co-Fe-B/MgO electrodes [20].

B. Bias dependence of the electroluminescence circular polarization

Figure 2(a) shows the variation of $P_c$ as a function of the current injected in the spin LEDs annealed at 300 °C for the sputtering and MBE samples. It appears clearly that $P_c$ is rather stable (just slightly decreasing) in the former case, whereas $P_c$ decreases abruptly when the current increases in the latter case. We observe that this trend does not depend on the annealing temperature $T_{an}$ in the range 200 °C–350 °C [the inset of Fig. 2(a) shows, for example, very similar dependences of $P_c$ as a function of current for sputtering samples annealed at 200 °C, 270 °C, and 300 °C].

We also measure $P_c$ as a function of $V_{bias}$ applied to the spin LEDs [Fig. 2(b)], which reveals the same trend as the current dependence. Concerning the dependence of the circular polarization of EL as a function of $V_{bias}$, several investigations have been performed previously on spin LEDs based on Schottky barriers [7,28,29] or oxide barriers [6,27,30].

For a thin Schottky barrier based on a highly $n$-doped semiconductor layer at the interface, it has been demonstrated that a very significant part of the bias drops on the semiconductor emitting zone—even in the regime of photon emission. In this case, the dependence of the electroluminescence circular polarization on bias is usually explained by the complex bias dependence of the ratio $\tau/\tau_s$ between the electron lifetime $\tau$ and the electron spin-relaxation time $\tau_s$ in the emitting zone [7,29].

For oxide tunnel barriers, the applied bias drops on the $p-i-n$ part of the device during a first step. Once enough holes are accumulated at the oxide-semiconductor interface [30] [see Fig. 5(b)], the bias drops also on the oxide barrier, allowing the bending of the tunnel barrier and the alignment of the semiconductor conduction band on the ferromagnetic-metal Fermi level. Then electrons start to be efficiently injected from the ferromagnetic to the semiconductor system and electroluminescence appears: we have confirmed this general trend for our device using the self-consistent Poisson-Schrödinger code from Ref. [39] (see Fig. 4). The carriers are injected with increasing kinetic energy for increasing biases. Thus, these electrons can encounter a spin relaxation due to the Dyakonov-Perel mechanism [40], leading to the decreasing behavior of the electroluminescence circular polarization as a function of the applied voltage [6,27,30].

From a general point of view, the electroluminescence circular-polarization rate detected in the quantum well can
be written as \( P_c = P_0 \left( \frac{E_k}{1 + \tau/\tau_s} \right) \). \( \tau \) and \( \tau_s \) are the electron lifetime and the electron spin-relaxation time in the (In,Ga)As/GaAs QW, respectively. \( P_0 \left( E_k \right) \) is the electron spin polarization just beneath the MgO/GaAs interface when the electrons have been injected with a kinetic energy \( E_k \) and have thermalized in the bottom of the conduction band. As shown in Fig. 2(b), \( P_c \) clearly decreases faster for MBE spin LEDs when increasing \( V_{bias} \). The fact that we observe no Stark shift on the XH transition of the quantum well (see Fig. 3) for the two types of samples indicates that the applied bias does not drop in the intrinsic region of the p-i-n junction once the bias threshold required to get electroluminescence is reached. One can thus consider that the variation of the ratio \( \tau/\tau_s \) due to a variation of electric field on the QW is not responsible for the observed decays of \( P_c \) as a function of bias or current.

C. Evidence of the parasitic hole current tunneling through MgO barriers

The overall differing qualitative behavior of the decrease of \( P_c \) as a function of bias (or current) in the two different samples (MBE and sputtering) could originate from a nonequivalent balance of the biases that drop, respectively, on the tunnel barrier and on the semiconductor part of the devices. This point is linked to the existence of a weak or large hole parasitic current flowing through the MgO tunnel barrier. Indeed, as explained in Ref. [30] for spin LEDs based on oxide tunnel barriers, the total current flowing in the device contains a parasitic current due to electrons that cross the tunnel barrier from the metal to the valence band of the semiconductor. It can be seen equivalently as a hole current flowing from the GaAs valence band to Co-Fe-B through MgO [see Fig. 5(b)]. This parasitic channel can be considered a shunt resistor in parallel to the tunnel barrier. In this picture, this current is smaller for the MBE sample. Because of this weak shunt, the voltage drop on the tunnel barrier is large. In principle, a reduced leakage current induces a smaller threshold current to get electroluminescence [30]. We do indeed observe this effect. Figure 5(a) shows the EL intensity as a function of the current through the device for both kinds of samples. We observe that the EL intensity is smaller for the MBE spin LED. As the voltage drop on the tunnel barrier is larger for this sample, the initial kinetic energy \( E_k \) is larger for a given bias voltage compared to the sputtering samples. As in bulk III–V semiconductors, the Dyakonov-Perel spin-relaxation-process efficiency increases with \( E_k \) [31,40], and it leads to a polarization
$P_0 (E_k)$ strongly decreasing when the applied bias increases for the MBE sample. This trend could explain the observed clear decay of EL circular polarization as a function of the applied bias or current (Fig. 2) [41].

For the sputtering samples, the leakage parasitic current is stronger, as is the shunt effect (the measured EL threshold is larger than the one for the MBE sample), so the voltage drop on the tunnel barrier is smaller for a given total applied voltage $V_{bias}$. The efficiency of the Dyakonov-Perel mechanism is thus weaker, and it leads to a $P_0 (E_k)$ slightly decreasing when the applied bias increases [Fig. 2(b)]. Note that the comparison of $I(V_{bias})$ characteristics for the two samples indicates that the current is larger in the sputtering sample [see the inset in Fig. 2(b)] for the range of biases explored. A significant part of the current may be caused by the parasitic leakage tunnel current through the MgO barrier.

D. Comparison of MgO barrier height for holes in the two types of tunnel barriers

A larger parasitic hole tunnel current for sputtering samples can have different origins. First, part of this current could be due to the presence of localized interface states and/or defect states (IS) at the MgO/GaAs interface [27] [see Fig. 5(b)]. The density of these states could differ between the full MBE-grown GaAs/MgO interface and the one obtained by a mixed growth method (MBE and sputtering) where a chamber transfer occurs. Second, part of the parasitic current could also be due to a direct tunneling of holes [27,30] through MgO [see Fig. 5(b)] and would thus depend on the height of the MgO tunnel barrier seen by the holes, which could be varied with the MgO growth process.

In order to go further in the understanding of the interface, we study the room-temperature electrical properties of a Au/MgO(2.5 nm)/n-doped ($n = 5 \times 10^{16}$ cm$^{-3}$) GaAs(001) structure annealed at 300$^\circ$C using CV methods. The MgO barriers have been prepared either by MBE or by sputtering methods, as those of the spin LED. Practical details about the CV experiments can be found in Ref. [43].

First, the analysis of CV measurements proves, for both kinds of samples, the existence of interface states (extracted using Terman’s method [44]) in the upper-half part of the band gap with a density of states (DOS) larger than about $3 \times 10^{17}$ states/eV m$^2$. However, as the DOSs are quite similar for both kinds of samples, the presence of these states, if taken alone, cannot explain the difference in the EL thresholds. Let us now examine the height $h_{hole}$ of the hole tunnel barriers for each sample [see the inset in Fig. 5(e)]. This height $h_{hole}$ can be expressed as $h_{hole} = E_{GaAs}^{MgO} - (E_{GaAs}^{GaAs} - \phi_B) - E_{offset}$, where $E_{GaAs}^{MgO}$ and $E_{GaAs}^{GaAs}$ are the band gaps of MgO and GaAs, respectively, and $E_{offset}$ is the band offset between the Co-Fe-B Fermi level and the bottom of the conduction band of MgO at the Co-Fe-B/MgO interface; $\phi_B$ is defined by the energy difference between the position of the bottom of the conduction band of GaAs at the MgO/GaAs interface and the Fermi level at zero bias.

Figure 5(e) shows the $1/C^2$ curves extracted from the high-frequency (1 MHz) CV curves measured at room temperature with MgO layers deposited either by MBE or by sputtering. Under reverse-bias voltages, the linear dependence of the $1/C^2$ versus bias voltage shows that the metal-oxide-semiconductor structures operate under depletion or deep-depletion mode. The barrier heights are calculated from the $1/C^2$ versus bias voltage using the following relation, $\phi_B = eV_I + k_B T + \xi$, where $V_I$ is the voltage intercept of the extrapolated $1/C^2$ curve with the voltage axis, $e$ is the elementary charge, and $k_B$ is the Boltzmann constant. $\xi = k_B T \ln(\frac{N_c}{N_d})$ is the difference between the energies of the bottom of conduction band and the Fermi level in bulk GaAs ($\xi = 56$ meV). Here, $N_d$ is the donor concentration and $N_c = 2/h^3(2\pi m^* k_B T)^{3/2}$ is the effective density of states, where $h$ is Planck’s constant and $m^*$ is the effective mass for conduction electrons in the zone center. We find that $\phi_B$ is larger for a MBE sample (1.00 eV) than for a sputtering sample (0.73 eV). These distinct values confirm that MgO/GaAs interfaces are clearly different from one growth technique to another.

If one assumes a comparable band offset $E_{offset}$ for the two types of samples, a weaker value for $\phi_B$ for sputtering samples (0.73 instead of 1.00 eV for MBE samples) directly leads to a smaller tunnel-barrier height $h_{hole}$ for the holes, which would explain the existence of a larger parasitic hole current for these sputtering samples. (Moreover, previous studies have demonstrated that the band offset $E_{offset}$ can also depend on the MgO growth technique [45].) Hence, we conclude that the difference of hole tunnel-barrier height is more likely responsible for the difference in the EL threshold between samples grown by MBE and by sputtering.

E. Electroluminescence circular polarization and intensity

As electrons are injected with a lower kinetic energy for the sputtering sample, their capture by the quantum well is more efficient [46] than in the case of the MBE sample. This finding could explain that, at higher currents [>1.5 mA; see Fig. 5(c)], the intensity of EL of the sputtering sample surpasses that of the MBE sample. Finally, we plot the figure of merit of $P_c$ versus the EL intensity in Fig. 5(d). It appears to be clear that the compromise between high $P_c$ and high EL intensity (for comparable electrical power consumption of the two samples, e.g., 2.3 mW for the sputtering sample instead of 3.8 mW for the MBE sample at $I = 1$ mA) is strongly dependent on the MgO growth process. Note that all of the trends reported for our samples with $T_{an} = 300^\circ$C are also observed for samples with $T_{an} = 350^\circ$C (not shown).
IV. CONCLUSION

In this paper, we investigate the influence of the MgO/GaAs interface on the current and bias dependence of the electrical spin injection into an (In,Ga)As/GaAs quantum-well light-emitting diode using textured MgO tunnel barriers fabricated either by sputtering or by MBE. An original point of this work is to use the complementary technique of capacitance-voltage measurements in addition to electroluminescence to get a deeper understanding of the metal/MgO/GaAs interface. We attribute the different behaviors observed on the two types of samples to the different kinetic energies of the injected carriers that result from the different Co-Fe-B/MgO/GaAs interfaces.

In view of future applications, our results show that the compromise between high electroluminescence circular polarization and high electroluminescence intensity can be modified by changing the MgO growth process. Here we reported on how the bias dependence of spin injection can be engineered thanks to different growth techniques of the MgO/GaAs interface. Finally, the understanding of the dependence of the spin-injection efficiency as a function of the applied bias would strongly benefit from the study of a three-terminal device [47] in order to apply or measure independently the voltage drops on the tunnel barrier and on the semiconductor part of the device [48].

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BIAS DEPENDENCE OF THE ELECTRICAL SPIN …

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[44] For example, a larger $E_{\text{offset}}$ (of approximately 0.5 eV) was observed by P.G. Mather, J.C. Read, and R.A. Buhrman, Disorder, defects, and band gaps in ultrathin (001)MgO tunnel barrier layers, Phys. Rev. B 73, 205412 (2006) for sputtering MgO than for electron-beam-evaporated MgO in Fe/MgO/Fe structures. This difference would also induce a smaller $h_{\text{hole}}$ for sputtering samples.


[48] Note that taking an Ohmic contact at the MgO/GaAs interface requires a strong $n$ doping of GaAs at the interface. This strong doping would clearly modify the device from the point of view of its band scheme, and it could lead to a nonoptimal device from the point of view of the spin transport itself.